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Data sheet

SAW duplexer

Part number: M5307 Ordering code: B39781M5307D310 Date: February 15, 2022

Version:

February 15, 2022 2.0

DCN: 80-PA243-614 Rev. A

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February 15, 2022

1 Application

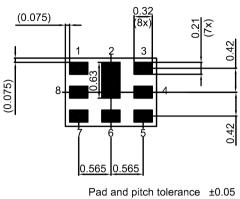
- Duplexer for higher part of Band 28
- LTE band 28b uplink: 733 MHz (pass band 30 MHz)
- LTE band 28b downlink: 788 MHz (pass band 30 MHz)

2 Features

- Package size 1.6±0.05 mm × 1.2±0.05 mm
- Package height 0.61±0.032 mm
- Approximate weight 3 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

3 Package

BOTTOM VIEW

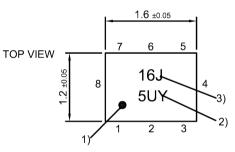


4 Pin configuration

- ∎ 1 RX
- ∎ 3 TX
- 6 ANT
- 2, 4, 5, 7, Ground 8

SIDE VIEW





1) Marking for pad number 1

2) Example of encoded lot number

3) Example of encoded filter type number

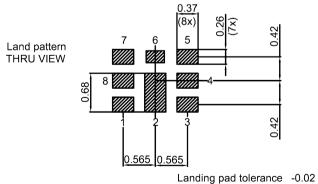
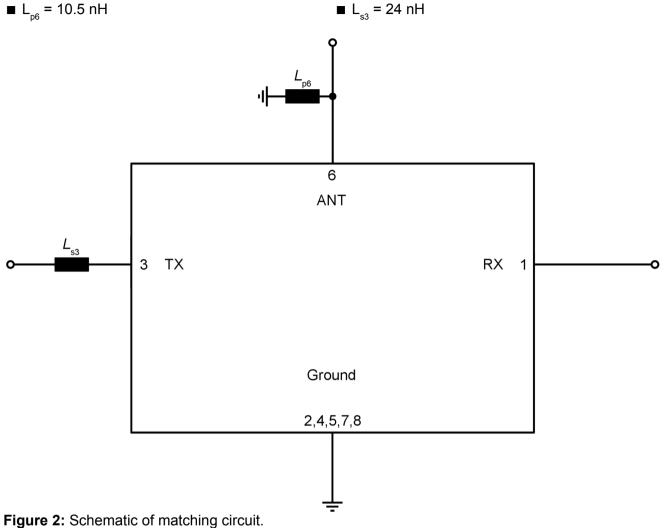


Figure 1: Drawing of package with package height A = $0.61_{\pm 0.032}$ mm. See Sec. Package information (p. 21).



Matching circuit 5

■ L_{n6} = 10.5 nH



6 Characteristics

6.1 TX – ANT

Temperature range for specification	$T_{_{\rm SPEC}}$	= −30 °C +85 °C
TX terminating impedance	Z _{TX}	= 50 Ω + 24 nH ¹⁾
ANT terminating impedance	Z _{ANT}	= 50 Ω // 10.5 nH ¹⁾
RX terminating impedance	Z _{RX}	= 50 Ω

Characteristics TX – ANT				min. for $T_{\rm SPEC}$	typ. @ +25 °C	max. for $T_{_{\rm SPEC}}$	
Center frequency			f _c	_	733	_	MHz
Maximum insertion attenuation			$\alpha_{_{max}}$				
	718.24 747.76	MHz		_	1.5	1.7 ²⁾	dB
	718.24 747.76	MHz		—	1.5	2.0	dB
Amplitude ripple (p-p)			Δα				
	718.24 747.76	MHz		—	1.1	1.5	dB
Maximum VSWR			$VSWR_{_{max}}$				
@ TX port	718 748	MHz		—	1.6	2.0	
@ ANT port	718 748	MHz		—	1.6	2.0	
Minimum attenuation			$\alpha_{_{min}}$				
	10 698	MHz		30	36	_	dB
	698 710	MHz		15	41	_	dB
	758.24 772.76	MHz		30	50	—	dB
	773.24 802.76	MHz		50	56	—	dB
	803 894	MHz		30	36	—	dB
	894 960	MHz		27	29	—	dB
	1166 1250	MHz		33	38	—	dB
	1406 1606	MHz		38	46	—	dB
	1710 3300	MHz		43	50	—	dB
	3300 6000	MHz		40	52	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Valid for typical temperature T = +25 °C.

ANT – RX 6.2

Temperature range for specification	$T_{_{ m SPEC}}$	= −30 °C +85 °C
TX terminating impedance	Z _{TX}	= 50 Ω + 24 nH ¹⁾
ANT terminating impedance	Z _{ANT}	= 50 Ω // 10.5 nH ¹⁾
RX terminating impedance	Z _{RX}	= 50 Ω

Characteristics ANT – RX				min. for $T_{_{ m SPEC}}$	typ. @ +25 °C	max. for $T_{_{ m SPEC}}$	
Center frequency			f _c	_	788	_	MHz
Maximum insertion attenuation			$\alpha_{_{max}}$				
	773.24 802.76	MHz		_	1.7	2.0	dB
Amplitude ripple (p-p)			Δα				
	773.24 802.76	MHz		_	1.1	1.5	dB
Maximum VSWR			$VSWR_{max}$				
@ ANT port	773 803	MHz		_	1.7	2.0	
@ RX port	773 803	MHz		_	1.7	2.0	
Minimum attenuation			$\alpha_{_{min}}$				
	100 699	MHz		45	55	_	dB
	703.24 747.76	MHz		50	55	_	dB
	814 835	MHz		7	15	_	dB
	835 1700	MHz		30	35	—	dB
	1700 6000	MHz		40	48	—	dB

6.3 TX – RX

Temperature range for specification	$T_{_{\rm SPEC}}$	= −30 °C +85 °C
TX terminating impedance	Z _{TX}	= 50 Ω + 24 nH ¹⁾
ANT terminating impedance	Z	= 50 Ω // 10.5 nH ¹⁾
RX terminating impedance	Z _{RX}	= 50 Ω

Characteristics TX – RX			min. for $T_{_{\rm SPEC}}$	typ. @ +25 °C	max. for T _{SPEC}	
Minimum isolation		α	n			
	718.24 747.76	MHz	55	58	—	dB
	773.24 802.76	MHz	55	60	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

7 Maximum ratings

Operable temperature	T _{OP} = −40 °C +125 °C	
Storage temperature	<i>T</i> _{STG} ¹⁾ = −40 °C +125 °C	
DC voltage	$ V_{\rm DC} ^{2} = 0 V (max.)$	
Input power @ TX port: 718 748 MHz	P _{IN} = 29 dBm	Continuous wave for 5000 h @ 50 °C.

¹⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

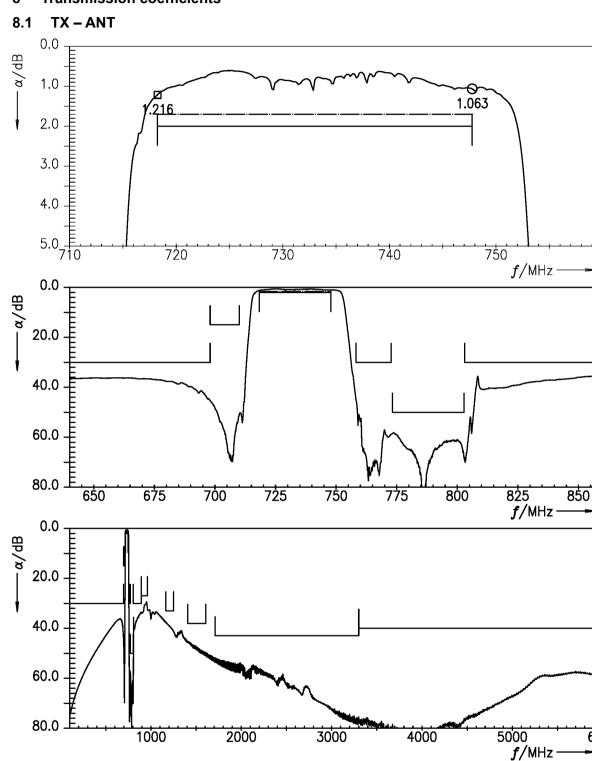
²⁾ In case of applied DC voltage blocking capacitors are mandatory.

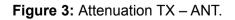


760

6000

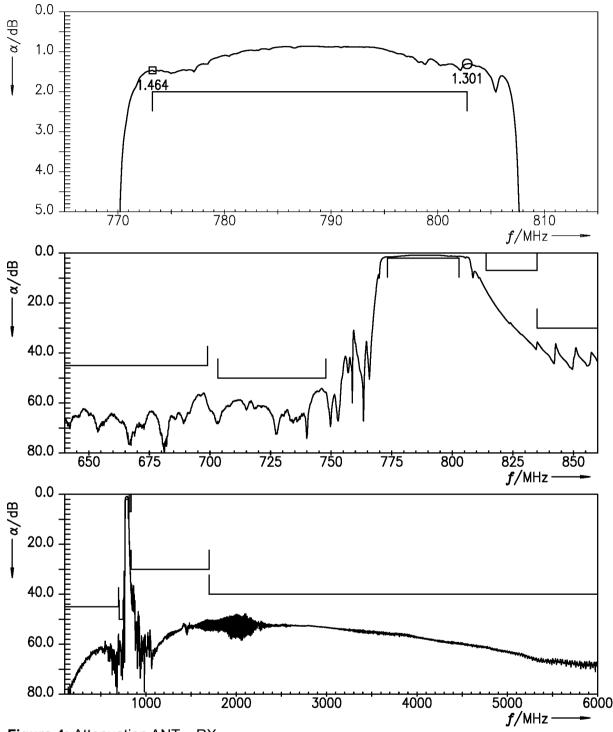
8 Transmission coefficients

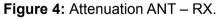




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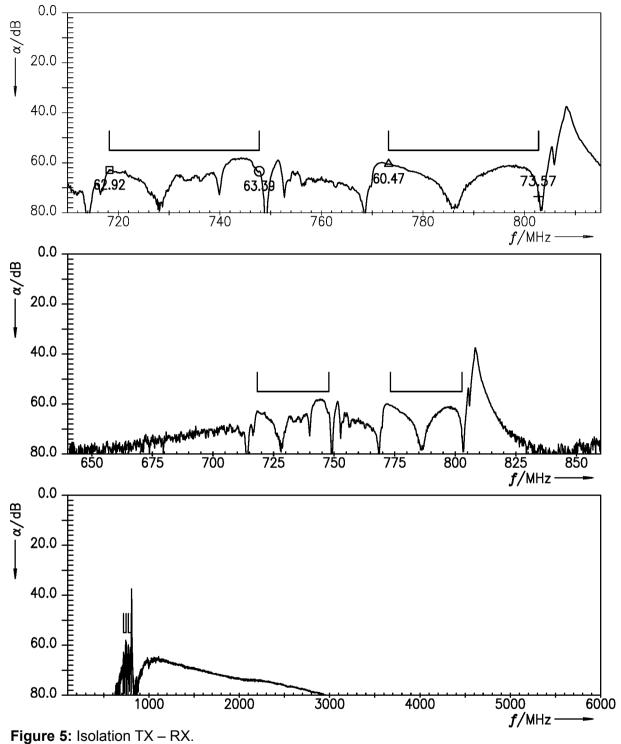






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□ = 718.0 O = 748.0

Z_{TX}=50 Ω

9 **Reflection coefficients**

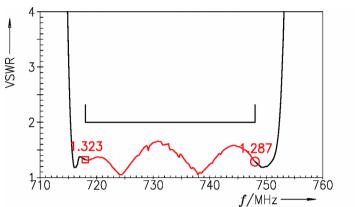
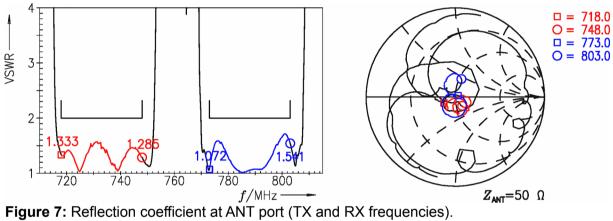


Figure 6: Reflection coefficient at TX port.



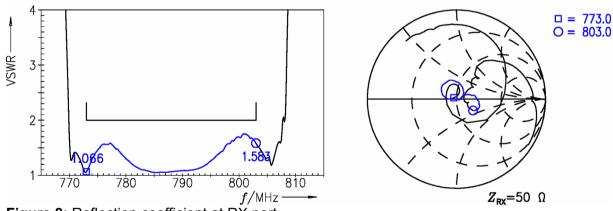
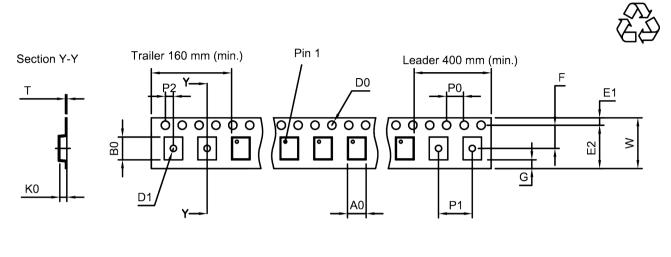


Figure 8: Reflection coefficient at RX port.



10 Packing material

10.1 Tape



User direction of unreeling

Figure 9: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	1.4±0.05 mm
B ₀	1.8±0.05 mm
D ₀	1.5+0.1/-0 mm
D ₁	0.6+0.1/-0 mm
E1	1.75±0.1 mm

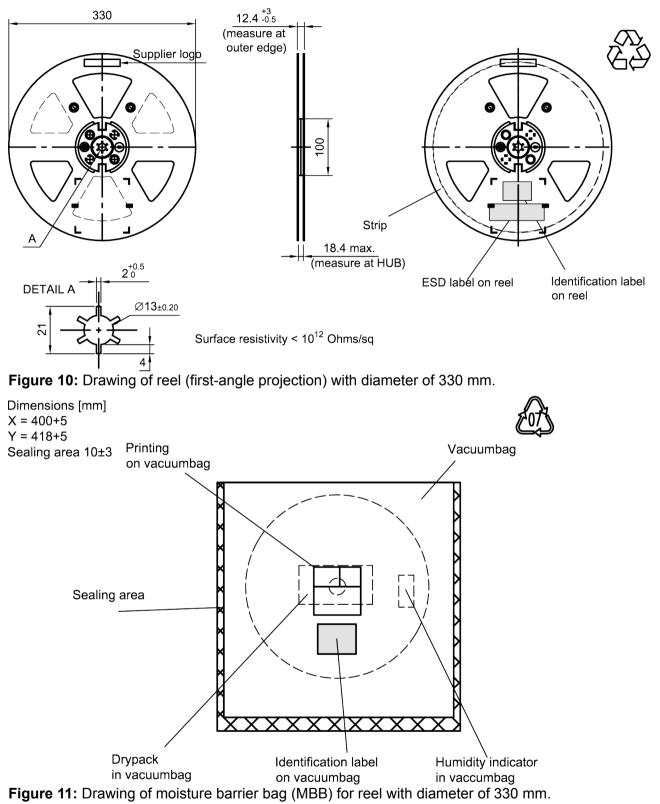
Table 1: Tape dimensions.

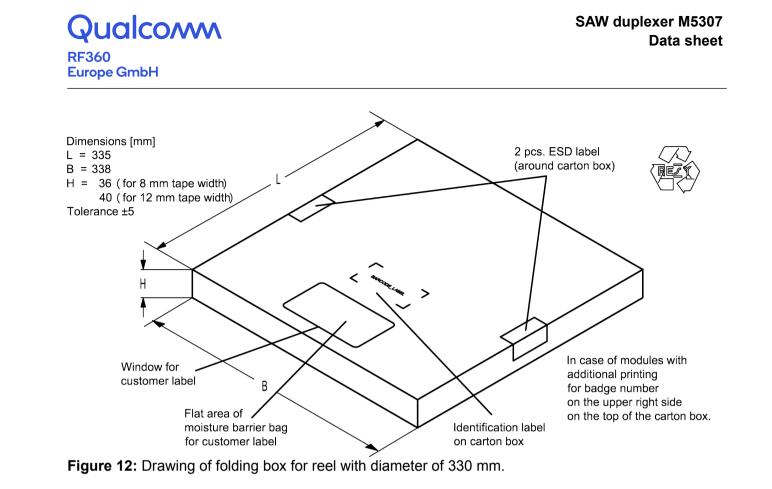
E2	10.25+0.2/-0 mm
F	5.5±0.05 mm
G	0.75 mm (min.)
K ₀	0.78±0.1 mm
P ₀	4.0±0.1 mm

P ₁	4.0±0.1 mm
P ₂	2.0±0.05 mm
Т	0.3±0.03 mm
W	12.0+0.3/-0.1 mm

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10.2 Reel with diameter of 330 mm





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11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, is encoded by a special BASE32 code into a 3 digit r	e.g., B3xxxxB <u>1234</u> xxxx,	
Example of decoding type number marking on a		in decimal code.
16J	=>	1234
1 x 32 ² + 6 x 32 ¹ + 18 (=J) x 32 ⁰	=	1234
The BASE32 code for product type M5307 is 55V.		
Lot number:		

Lot number:

> The last 5 digits of the lot number, 12345, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device

ple of decoding lot number marking on device		in decimal code.
5UY	=>	12345
5 x 47 ² + 27 (=U) x 47 ¹ + 31 (=Y) x 47 ⁰	=	12345

Adopted BASE32 code for type number				
Decimal	Base32	Decimal	Base32	
value	code	value	code	
0	0	16	G	
1	1	17	Н	
2	2	18	J	
3	3	19	K	
4	4	20	М	
5	5	21	N	
6	6	22	Р	
7	7	23	Q	
8	8	24	R	
9	9	25	S	
10	A	26	Т	
11	В	27	V	
12	С	28	W	
13	D	29	Х	
14	E	30	Y	
15	F	31	Z	

Adopted BASE47 code for lot number				
Decimal	Base47	Decimal	Base47	
value	code	value	code	
0	0	24	R	
1	1	25	S	
2	2	26	Т	
3	3	27	U	
4	4	28	V	
5	5	29	W	
6	6	30	Х	
7	7	31	Y	
8	8	32	Z	
9	9	33	b	
10	А	34	d	
11	В	35	f	
12	С	36	h	
13	D	37	n	
14	E	38	r	
15	F	39	t	
16	G	40	v	
17	Н	41	١	
18	J	42	?	
19	К	43	{	
20	L	44	}	
21	М	45	<	
22	N	46	>	
23	Р			

Table 2: Lists for encoding and decoding of marking.

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

≤ 3 K/s
125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
30 s to 70 s
min. 10 s
max. 20 s
-
250 °C +0/-5 °C
230 °C +5/-0 °C for 10 s ± 1 s
≤ 3 K/s
measured at solder pads

 Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

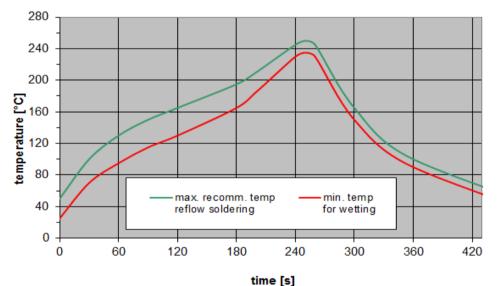


Figure 13: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under https://rffe.gualcomm.com/.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.



15 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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